

In the Claims

Please rewrite claims 4, 13 and 17 as follows:

*Q2* 4. (Amended) A package as in claim 1, further comprising an element which allows sealing said integrated circuit relative to an environment of said package.

13. (Amended) A package for an integrated circuit, comprising:

*Q3* a packaging portion, having an outer perimeter with a metal contact portion thereon, and an inner perimeter, said inner perimeter formed by a downward facing surface with a metal contact thereon, said metal contact being adapted to connect to an integrated circuit and a bottom and sideward facing surface also having said metal contact portion thereon, said contact portion extending from said outer perimeter to said downward facing surface.

*Q4* 17. (Amended) A package as in claim 16, further comprising a backing area, hermetically sealing a bottom portion, and wherein said metal contact is disposed around said bottom portion.